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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc67-04i-pq

PIC16C6X

TABLE 3-1: PIC16C61 PINOUT DESCRIPTION

Pin Name	DIP Pin#	SOIC Pin#	Pin Type	Buffer Type	Description
OSC1/CLKIN	16	16	I	ST/CMOS ⁽¹⁾	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	4	4	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.
RA0 RA1 RA2 RA3 RA4/T0CKI	17 18 1 2 3	17 18 1 2 3	I/O I/O I/O I/O I/O	TTL TTL TTL TTL ST	PORTA is a bi-directional I/O port. RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
RB0/INT RB1 RB2 RB3 RB4 RB5 RB6 RB7	6 7 8 9 10 11 12 13	6 7 8 9 10 11 12 13	I/O I/O I/O I/O I/O I/O I/O I/O	TTL/ST ⁽²⁾ TTL TTL TTL TTL TTL TTL/ST ⁽³⁾ TTL/ST ⁽³⁾	PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs. RB0 can also be the external interrupt pin. Interrupt on change pin. Interrupt on change pin. Interrupt on change pin. Serial programming clock. Interrupt on change pin. Serial programming data.
VSS	5	5	P	—	Ground reference for logic and I/O pins.
VDD	14	14	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
 — = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2: This buffer is a Schmitt Trigger input when configured as the external interrupt.

3: This buffer is a Schmitt Trigger input when used in serial programming mode.

4.2.2 SPECIAL FUNCTION REGISTERS:

The Special Function Registers are registers used by the CPU and peripheral modules for controlling the desired operation of the device. These registers are implemented as static RAM.

The special function registers can be classified into two sets (core and peripheral). The registers associated with the “core” functions are described in this section and those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: SPECIAL FUNCTION REGISTERS FOR THE PIC16C61

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on all other resets ⁽³⁾					
Bank 0																
00h ⁽¹⁾	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000					
01h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu					
02h ⁽¹⁾	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000					
03h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RPO	TO	PD	Z	DC	C	0001 1xxx	000q quuu					
04h ⁽¹⁾	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu					
05h	PORTA	—	—	—	PORTA Data Latch when written: PORTA pins when read					---x xxxx	---u uuuu					
06h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu					
07h	—	Unimplemented								—	—					
08h	—	Unimplemented								—	—					
09h	—	Unimplemented								—	—					
0Ah ^(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000					
0Bh ⁽¹⁾	INTCON	GIE	—	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0-00 000x	0-00 000u					
Bank 1																
80h ⁽¹⁾	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000					
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111					
82h ⁽¹⁾	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000					
83h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RPO	TO	PD	Z	DC	C	0001 1xxx	000q quuu					
84h ⁽¹⁾	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu					
85h	TRISA	—	—	—	PORTA Data Direction Register					---1 1111	---1 1111					
86h	TRISB	PORTB Data Direction Control Register								1111 1111	1111 1111					
87h	—	Unimplemented								—	—					
88h	—	Unimplemented								—	—					
89h	—	Unimplemented								—	—					
8Ah ^(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000					
8Bh ⁽¹⁾	INTCON	GIE	—	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0-00 000x	0-00 000u					

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented locations read as '0'.

Shaded locations are unimplemented and read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved on the PIC16C61, always maintain these bits clear.

5.3 PORTC and TRISC Register

Applicable Devices

61|62|62A|R62|63|R63|64|64A|R64|65|65A|R65|66|67

PORTC is an 8-bit wide bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (BSF, BCF, XORWF) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 5-3: INITIALIZING PORTC

```

BCF    STATUS, RP0      ;
BCF    STATUS, RP1      ; PIC16C66/67 only
CLRF   PORTC           ; Initialize PORTC by
                       ; clearing output
                       ; data latches
BSF    STATUS, RP0      ; Select Bank 1
MOVWF  0xCF             ; Value used to
                           ; initialize data
                           ; direction
MOVWF  TRISC            ; Set RC<3:0> as inputs
                           ; RC<5:4> as outputs
                           ; RC<7:6> as inputs

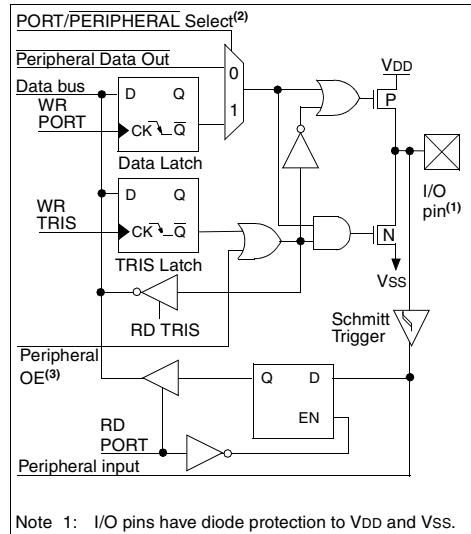
```

TABLE 5-5: PORTC FUNCTIONS FOR PIC16C62/64

Name	Bit#	Buffer Type	Function
RC0/T1OSI/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator input or Timer1 clock input
RC1/T1OSO	bit1	ST	Input/output port pin or Timer1 oscillator output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I ² C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	bit5	ST	Input/output port pin or synchronous serial port data output
RC6	bit6	ST	Input/output port pin
RC7	bit7	ST	Input/output port pin

Legend: ST = Schmitt Trigger input

FIGURE 5-6: PORTC BLOCK DIAGRAM



- Note 1: I/O pins have diode protection to VDD and Vss.
- 2: Port/Peripheral select signal selects between port data and peripheral output.
- 3: Peripheral OE (output enable) is only activated if peripheral select is active.

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FIGURE 5-12: PARALLEL SLAVE PORT WRITE WAVEFORMS

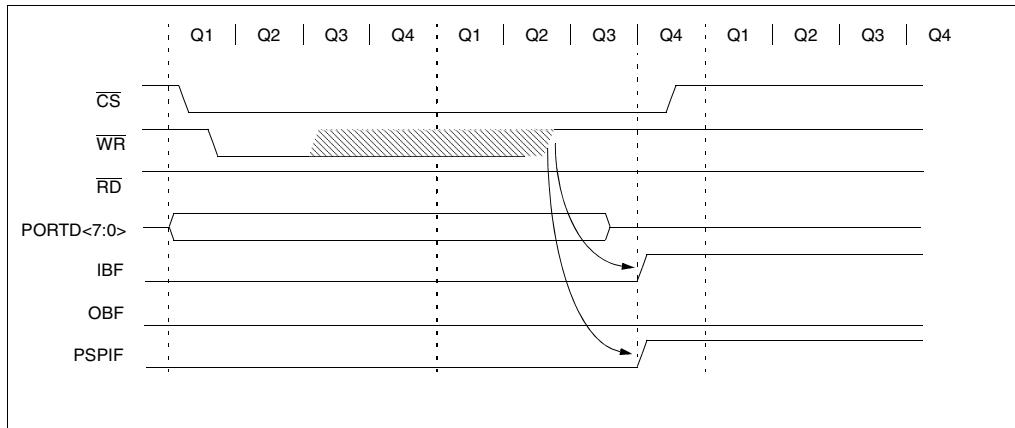


FIGURE 5-13: PARALLEL SLAVE PORT READ WAVEFORMS

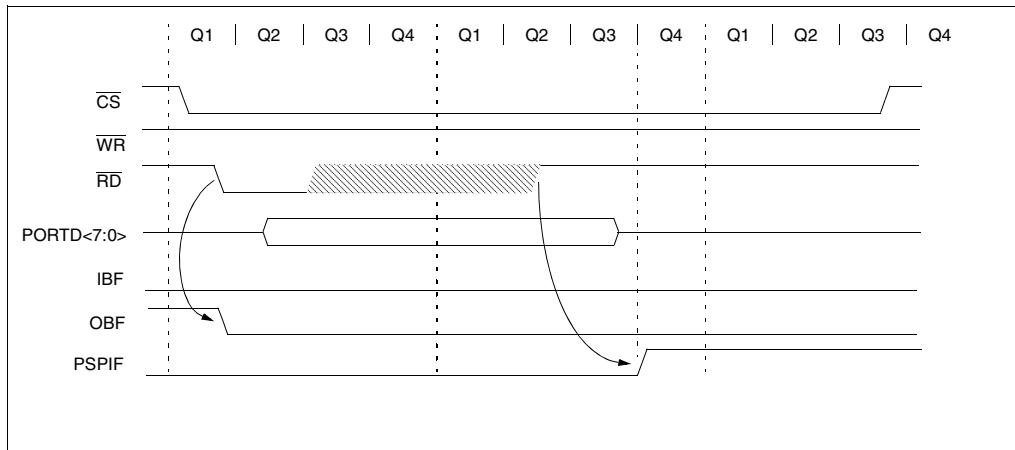


TABLE 5-13: REGISTERS ASSOCIATED WITH PARALLEL SLAVE PORT

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
08h	PORTD	PSP7	PSP6	PSP5	PSP4	PSP3	PSP2	PSP1	PSP0	xxxx xxxx	uuuu uuuu
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu
89h	TRISE	IBF	OBF	IBOV	PSPMODE	PORTE Data Direction Bits			0000 -111	0000 -111	
0Ch	PIR1	PSPIF	(1)	RCIF ⁽²⁾	TXIF ⁽²⁾	SSPIF	CCP1IF	TMR2IF	TRM1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE	(1)	RCIE ⁽²⁾	TXIE ⁽²⁾	SSPIE	CCP1IE	TMR2IE	TRM1IE	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by the PSP.

Note 1: These bits are reserved, always maintain these bits clear.

2: These bits are implemented on the PIC16C65/65A/R65/67 only.

6.0 OVERVIEW OF TIMER MODULES

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

All PIC16C6X devices have three timer modules except for the PIC16C61, which has one timer module. Each module can generate an interrupt to indicate that an event has occurred (i.e., timer overflow). Each of these modules are detailed in the following sections. The timer modules are:

- Timer0 module (Section 7.0)
- Timer1 module (Section 8.0)
- Timer2 module (Section 9.0)

6.1 Timer0 Overview

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

The Timer0 module is a simple 8-bit overflow counter. The clock source can be either the internal system clock ($F_{osc}/4$) or an external clock. When the clock source is an external clock, the Timer0 module can be selected to increment on either the rising or falling edge.

The Timer0 module also has a programmable prescaler option. This prescaler can be assigned to either the Timer0 module or the Watchdog Timer. Bit PSA (OPTION<3>) assigns the prescaler, and bits PS2:PS0 (OPTION<2:0>) determine the prescaler value. TMR0 can increment at the following rates: 1:1 when the prescaler is assigned to Watchdog Timer, 1:2, 1:4, 1:8, 1:16, 1:32, 1:64, 1:128, and 1:256.

Synchronization of the external clock occurs after the prescaler. When the prescaler is used, the external clock frequency may be higher than the device's frequency. The maximum frequency is 50 MHz, given the high and low time requirements of the clock.

6.2 Timer1 Overview

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

Timer1 is a 16-bit timer/counter. The clock source can be either the internal system clock ($F_{osc}/4$), an external clock, or an external crystal. Timer1 can operate as either a timer or a counter. When operating as a counter (external clock source), the counter can either operate synchronized to the device or asynchronously to the device. Asynchronous operation allows Timer1 to operate during sleep, which is useful for applications that require a real-time clock as well as the power savings of SLEEP mode.

Timer1 also has a prescaler option which allows TMR1 to increment at the following rates: 1:1, 1:2, 1:4, and 1:8. TMR1 can be used in conjunction with the Capture/Compare/PWM module. When used with a CCP module, Timer1 is the time-base for 16-bit capture or 16-bit compare and must be synchronized to the device.

6.3 Timer2 Overview

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

Timer2 is an 8-bit timer with a programmable prescaler and a programmable postscaler, as well as an 8-bit Period Register (PR2). Timer2 can be used with the CCP module (in PWM mode) as well as the Baud Rate Generator for the Synchronous Serial Port (SSP). The prescaler option allows Timer2 to increment at the following rates: 1:1, 1:4, and 1:16.

The postscaler allows TMR2 register to match the period register (PR2) a programmable number of times before generating an interrupt. The postscaler can be programmed from 1:1 to 1:16 (inclusive).

6.4 CCP Overview

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

The CCP module(s) can operate in one of three modes: 16-bit capture, 16-bit compare, or up to 10-bit Pulse Width Modulation (PWM).

Capture mode captures the 16-bit value of TMR1 into the CCPRxH:CCPRxL register pair. The capture event can be programmed for either the falling edge, rising edge, fourth rising edge, or sixteenth rising edge of the CCPx pin.

Compare mode compares the TMR1H:TMR1L register pair to the CCPRxH:CCPRxL register pair. When a match occurs, an interrupt can be generated and the output pin CCPx can be forced to a given state (High or Low) and Timer1 can be reset. This depends on control bits CCPxM3:CCPxMO.

PWM mode compares the TMR2 register to a 10-bit duty cycle register (CCPRxH:CCPRxL<5:4>) as well as to an 8-bit period register (PR2). When the TMR2 register = Duty Cycle register, the CCPx pin will be forced low. When TMR2 = PR2, TMR2 is cleared to 00h, an interrupt can be generated, and the CCPx pin (if an output) will be forced high.

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TABLE 10-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽²⁾	(3)	RCIF ⁽¹⁾	TXIF ⁽¹⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh ⁽⁴⁾	PIR2	—	—	—	—	—	—	—	CCP2IF	----- 0	----- 0
8Ch	PIE1	PSPIE ⁽²⁾	(3)	RCIE ⁽¹⁾	TXIE ⁽¹⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh ⁽⁴⁾	PIE2	—	—	—	—	—	—	—	CCP2IE	----- 0	----- 0
87h	TRISC	PORTC Data Direction register								1111 1111	1111 1111
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
92h	PR2	Timer2 module's Period register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
1Bh ⁽⁴⁾	CCPR2L	Capture/Compare/PWM2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch ⁽⁴⁾	CCPR2H	Capture/Compare/PWM2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh ⁽⁴⁾	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used in this mode.

Note 1: These bits are associated with the USART module, which is implemented on the PIC16C63/R63/65/65A/R65/66/67 only.

2: Bits PSPIE and PSPIF are reserved on the PIC16C62/62A/R62/63/R63/66, always maintain these bits clear.

3: The PIR1<6> and PIE1<6> bits are reserved, always maintain these bits clear.

4: These registers are associated with the CCP2 module, which is only implemented on the PIC16C63/R63/65/65A/R65/66/67.

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TABLE 12-3: BAUD RATES FOR SYNCHRONOUS MODE

BAUD RATE (K)	FOSC = 20 MHz			16 MHz			10 MHz			7.15909 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	NA	-	-	NA	-	-	NA	-	-	NA	-	-
2.4	NA	-	-	NA	-	-	NA	-	-	NA	-	-
9.6	NA	-	-	NA	-	-	9.766	+1.73	255	9.622	+0.23	185
19.2	19.53	+1.73	255	19.23	+0.16	207	19.23	+0.16	129	19.24	+0.23	92
76.8	76.92	+0.16	64	76.92	+0.16	51	75.76	-1.36	32	77.82	+1.32	22
96	96.15	+0.16	51	95.24	-0.79	41	96.15	+0.16	25	94.20	-1.88	18
300	294.1	-1.96	16	307.69	+2.56	12	312.5	+4.17	7	298.3	-0.57	5
500	500	0	9	500	0	7	500	0	4	NA	-	-
HIGH	5000	-	0	4000	-	0	2500	-	0	1789.8	-	0
LOW	19.53	-	255	15.625	-	255	9.766	-	255	6.991	-	255

BAUD RATE (K)	FOSC = 5.0688 MHz			4 MHz			3.579545 MHz			1 MHz			32.768 kHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-	0.303	+1.14	26
1.2	NA	-	-	NA	-	-	NA	-	-	1.202	+0.16	207	1.170	-2.48	6
2.4	NA	-	-	NA	-	-	NA	-	-	2.404	+0.16	103	NA	-	-
9.6	9.6	0	131	9.615	+0.16	103	9.622	+0.23	92	9.615	+0.16	25	NA	-	-
19.2	19.2	0	65	19.231	+0.16	51	19.04	-0.83	46	19.24	+0.16	12	NA	-	-
76.8	79.2	+3.13	15	76.923	+0.16	12	74.57	-2.90	11	83.34	+8.51	2	NA	-	-
96	97.48	+1.54	12	1000	+4.17	9	99.43	+3.57	8	NA	-	-	NA	-	-
300	316.8	+5.60	3	NA	-	-	298.3	-0.57	2	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	1267	-	0	100	-	0	894.9	-	0	250	-	0	8.192	-	0
LOW	4.950	-	255	3.906	-	255	3.496	-	255	0.9766	-	255	0.032	-	255

TABLE 12-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD RATE (K)	FOSC = 20 MHz			16 MHz			10 MHz			7.15909 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	1.221	+1.73	255	1.202	+0.16	207	1.202	+0.16	129	1.203	+0.23	92
2.4	2.404	+0.16	129	2.404	+0.16	103	2.404	+0.16	64	2.380	-0.83	46
9.6	9.469	-1.36	32	9.615	+0.16	25	9.766	+1.73	15	9.322	-2.90	11
19.2	19.53	+1.73	15	19.23	+0.16	12	19.53	+1.73	7	18.64	-2.90	5
76.8	78.13	+1.73	3	83.33	+8.51	2	78.13	+1.73	1	NA	-	-
96	104.2	+8.51	2	NA	-	-	NA	-	-	NA	-	-
300	312.5	+4.17	0	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	312.5	-	0	250	-	0	156.3	-	0	111.9	-	0
LOW	1.221	-	255	0.977	-	255	0.6104	-	255	0.437	-	255

BAUD RATE (K)	FOSC = 5.0688 MHz			4 MHz			3.579545 MHz			1 MHz			32.768 kHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	0.31	+3.13	255	0.3005	-0.17	207	0.301	+0.23	185	0.300	+0.16	51	0.256	-14.67	1
1.2	1.2	0	65	1.202	+1.67	51	1.190	-0.83	46	1.202	+0.16	12	NA	-	-
2.4	2.4	0	32	2.404	+1.67	25	2.432	+1.32	22	2.232	-6.99	6	NA	-	-
9.6	9.9	+3.13	7	NA	-	-	9.322	-2.90	5	NA	-	-	NA	-	-
19.2	19.8	+3.13	3	NA	-	-	18.64	-2.90	2	NA	-	-	NA	-	-
76.8	79.2	+3.13	0	NA	-	-	NA	-	-	NA	-	-	NA	-	-
96	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
300	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	79.2	-	0	62.500	-	0	55.93	-	0	15.63	-	0	0.512	-	0
LOW	0.3094	-	255	3.906	-	255	0.2185	-	255	0.0610	-	255	0.0020	-	255

13.8 Power-down Mode (SLEEP)

Applicable Devices															
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, status bit \overline{PD} (STATUS<3>) is cleared, status bit \overline{TO} (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD, or VSS, ensure no external circuitry is drawing current from the I/O pin, and disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The MCLR/VPP pin must be at a logic high level (VIHMC).

13.8.1 WAKE-UP FROM SLEEP

The device can wake from SLEEP through one of the following events:

1. External reset input on MCLR/VPP pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, RB port change, or some peripheral interrupts.

External MCLR Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device reset. The \overline{PD} bit, which is set on power-up is cleared when SLEEP is invoked. The \overline{TO} bit is cleared if WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. SSP (Start/Stop) bit detect interrupt.
3. SSP transmit or receive in slave mode (SPI/I²C).
4. CCP capture mode interrupt.
5. Parallel Slave Port read or write.
6. USART TX or RX (synchronous slave mode).

Other peripherals can not generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

13.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the TO bit will not be set and \overline{PD} bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake up from sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the \overline{TO} bit will be set and the \overline{PD} bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the \overline{PD} bit. If the \overline{PD} bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
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15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C61

Absolute Maximum Ratings †

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, <u>MCLR</u> , and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	-0.3V to +7.5V
Voltage on <u>MCLR</u> with respect to Vss (Note 2)	0V to +14V
Voltage on RA4 pin with respect to Vss	0V to +14V
Total power dissipation (Note 1)	800 mW
Maximum current out of Vss pin	150 mA
Maximum current into VDD pin	100 mA
Input clamp current, <u>I_{IK}</u> (V _I < 0 or V _I > VDD)	± 20 mA
Output clamp current, <u>I_{OK}</u> (V _O < 0 or V _O > VDD)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA	80 mA
Maximum current sourced by PORTA	50 mA
Maximum current sunk by PORTB	150 mA
Maximum current sourced by PORTB	100 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = VDD \times \{IDD - \sum I_{OH}\} + \sum \{(VDD-V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

Note 2: Voltage spikes below Vss at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C61-04	PIC16C61-20	PIC16LC61-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 µA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 µA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 15 µA typ. at 32 kHz, 4.0V IPD: 0.6 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 32 µA max. at 32 kHz, 3.0V IPD: 9 µA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 32 µA max. at 32 kHz, 3.0V IPD: 9 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications.

It is recommended that the user select the device type that ensures the specifications required.

FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

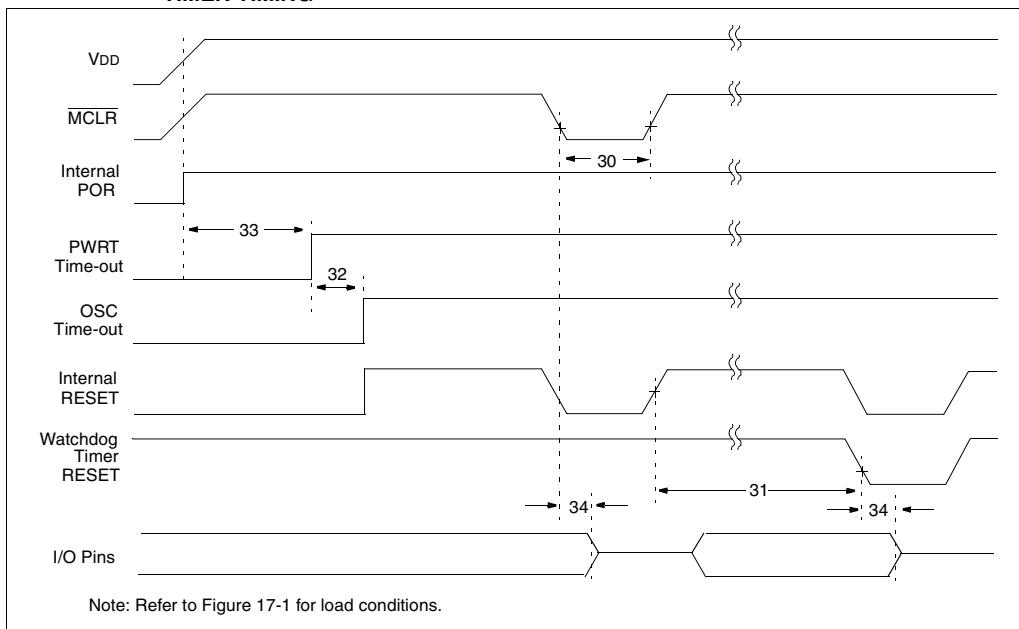


TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30*	Tmcl	MCLR Pulse Width (low)	100	—	—	ns	VDD = 5V, -40°C to +85°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc	—	—	Tosc = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +85°C
34*	Tioz	I/O Hi-impedance from MCLR Low	—	—	100	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

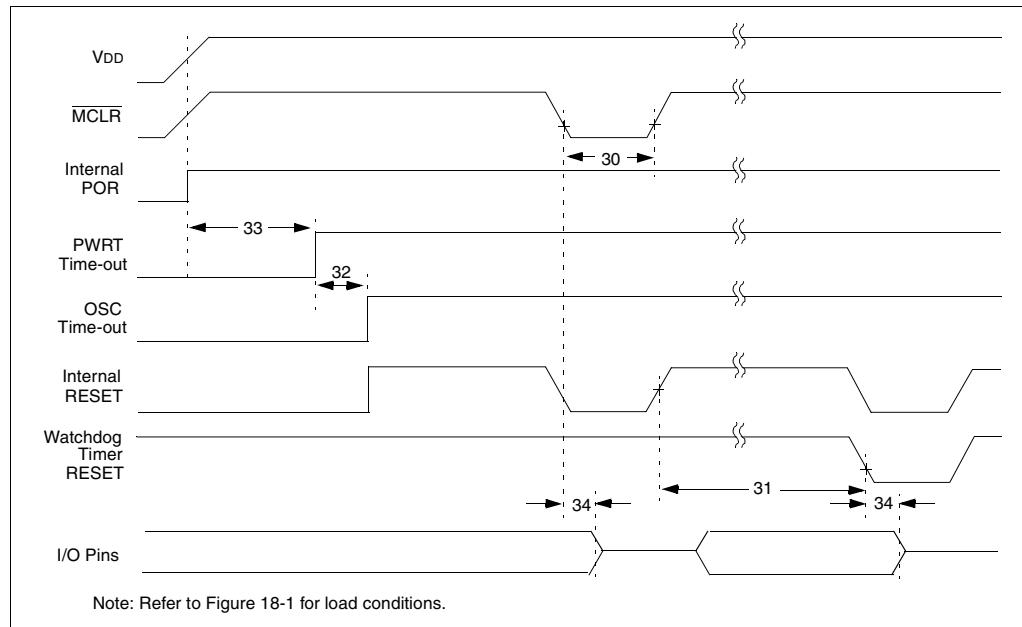


FIGURE 18-5: BROWN-OUT RESET TIMING



TABLE 18-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	T _{mcl}	MCLR Pulse Width (low)	2	—	—	μs	VDD = 5V, -40°C to +125°C
31*	T _{wdt}	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	T _{ost}	Oscillation Start-up Timer Period	—	1024T _{osc}	—	—	T _{osc} = OSC1 period
33*	T _{pwr}	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	T _{ioz}	I/O Hi-impedance from MCLR Low or WDT Reset	—	—	2.1	μs	
35	T _{bör}	Brown-out Reset Pulse Width	100	—	—	μs	VDD ≤ BVDD (param. D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-9: SPI MODE TIMING

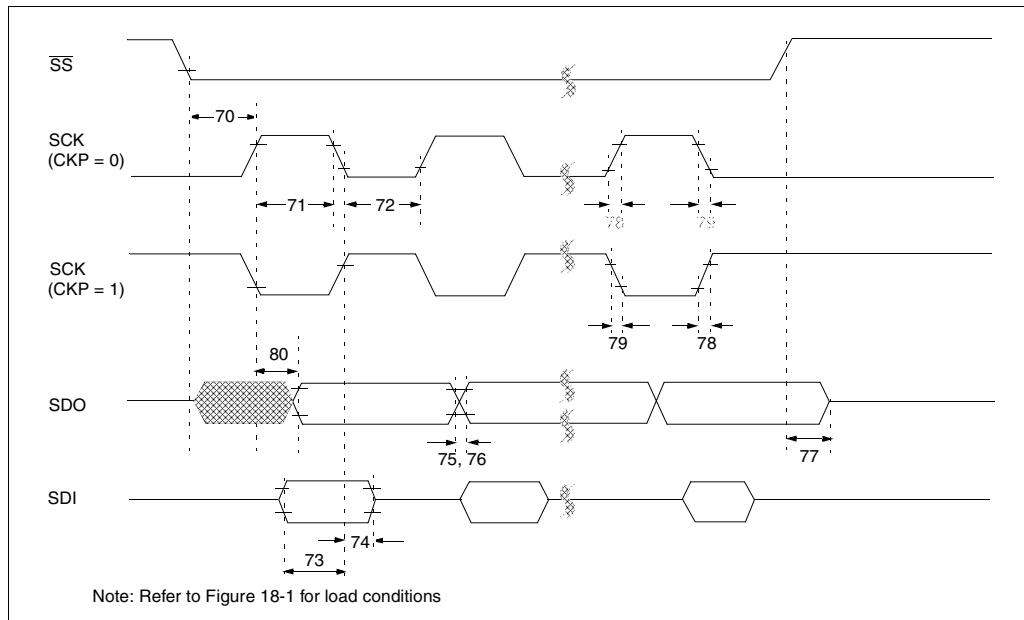


TABLE 18-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typt	Max	Units	Conditions
70*	TssL2scH, TssL2scL	SS↓ to SCK↓ or SCK↑ input	T _{CY}	—	—	ns	
71*	TscH	SCK input high time (slave mode)	T _{CY} + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	T _{CY} + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	SS↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

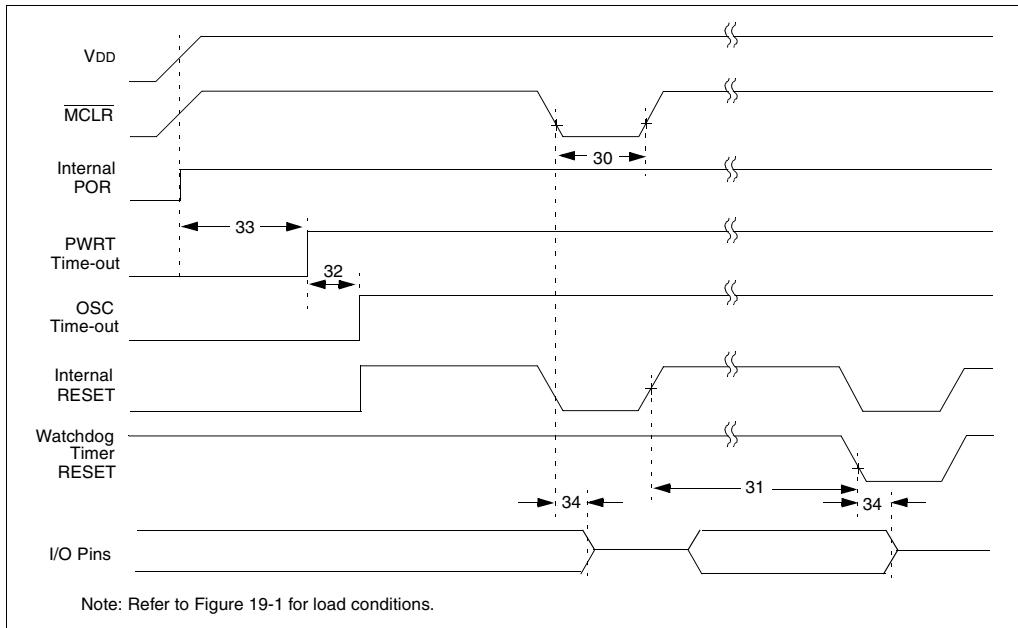


TABLE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30*	T _{mcl}	MCLR Pulse Width (low)	100	—	—	ns	V _{DD} = 5V, -40°C to +85°C
31*	T _{wdt}	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	V _{DD} = 5V, -40°C to +85°C
32	T _{ost}	Oscillation Start-up Timer Period	—	1024T _{osc}	—	—	T _{osc} = OSC1 period
33*	T _{pwr}	Power-up Timer Period or WDT reset	28	72	132	ms	V _{DD} = 5V, -40°C to +85°C
34	T _{ioz}	I/O Hi-impedance from MCLR Low	—	—	100	ns	

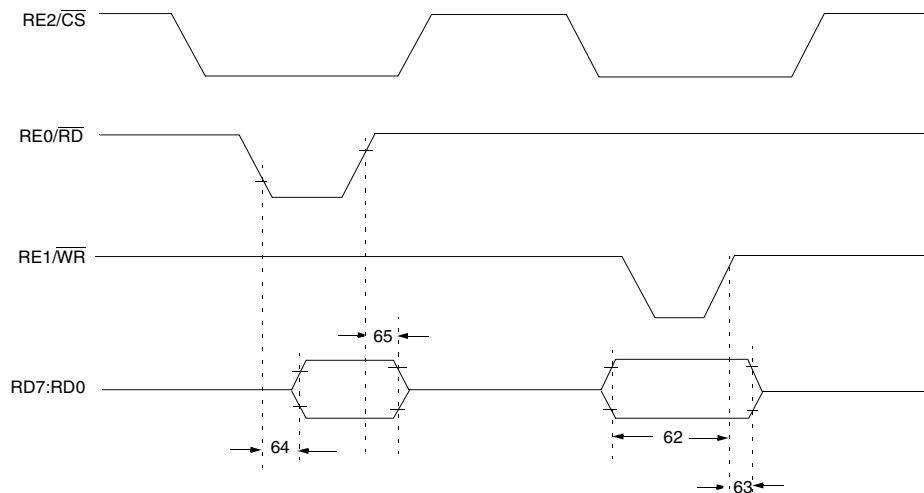
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C6X

Applicable Devices | 61 | 62 | 62A | R62 | 63 | R63 | 64 | 64A | R64 | 65 | 65A | R65 | 66 | 67 |

FIGURE 19-7: PARALLEL SLAVE PORT TIMING



Note: Refer to Figure 19-1 for load conditions

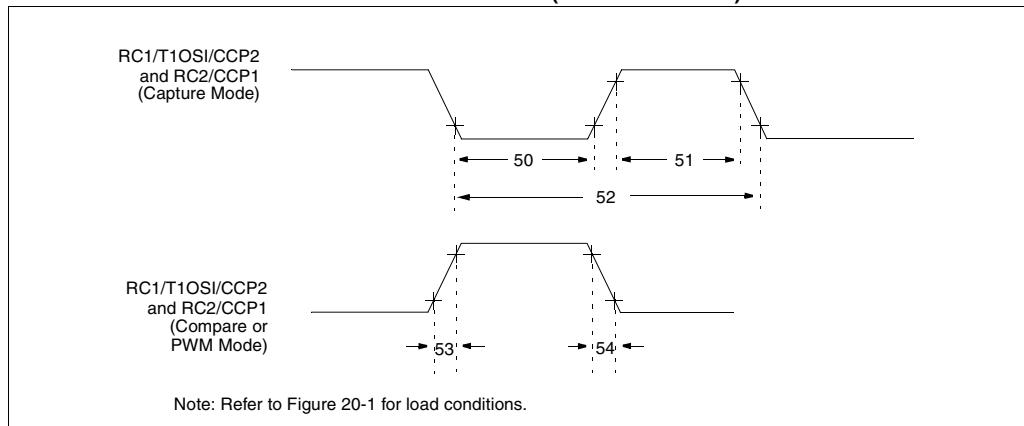
TABLE 19-7: PARALLEL SLAVE PORT REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before $\overline{WR} \uparrow$ or $\overline{CS} \uparrow$ (setup time)	20	—	—	ns	
63*	Twrh2dtl	$\overline{WR} \uparrow$ or $\overline{CS} \uparrow$ to data-in invalid (hold time)	PIC16C65	20	—	—	ns
				PIC16LC65	35	—	ns
64	TrdL2dtv	$\overline{RD} \downarrow$ and $\overline{CS} \downarrow$ to data-out valid		—	—	80	ns
65	Trdh2dtl	$\overline{RD} \uparrow$ or $\overline{CS} \uparrow$ to data-out invalid	10	—	30	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
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FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)**TABLE 20-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)**

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time		0.5TCY + 20	—	—	ns	
		With Prescaler	PIC16C63/65A	10	—	—		
			PIC16LC63/65A	20	—	—		
51*	TccH	CCP1 and CCP2 input high time		0.5TCY + 20	—	—	ns	
		With Prescaler	PIC16C63/65A	10	—	—		
			PIC16LC63/65A	20	—	—		
52*	TccP	CCP1 and CCP2 input period		$\frac{3TCY + 40}{N}$	—	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 output rise time		PIC16C63/65A	—	10	25	ns
			PIC16LC63/65A	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16C63/65A	—	10	25	ns
			PIC16LC63/65A	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 21-9: SPI MODE TIMING

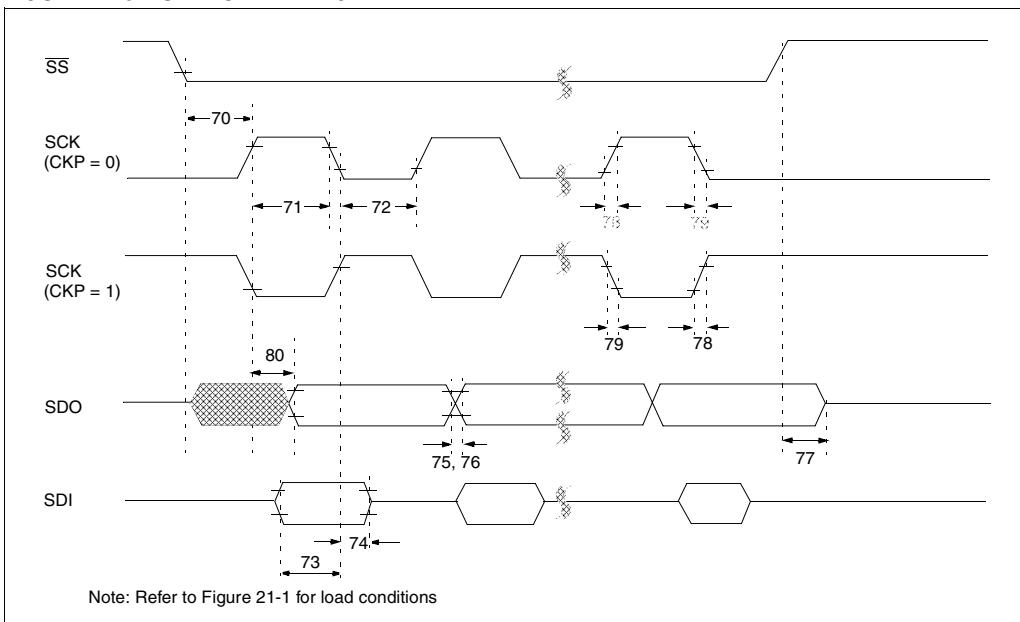


TABLE 21-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typt	Max	Units	Conditions
70*	TssL2scH, TssL2scL	SS _↓ to SCK _↓ or SCK _↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	SS _↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

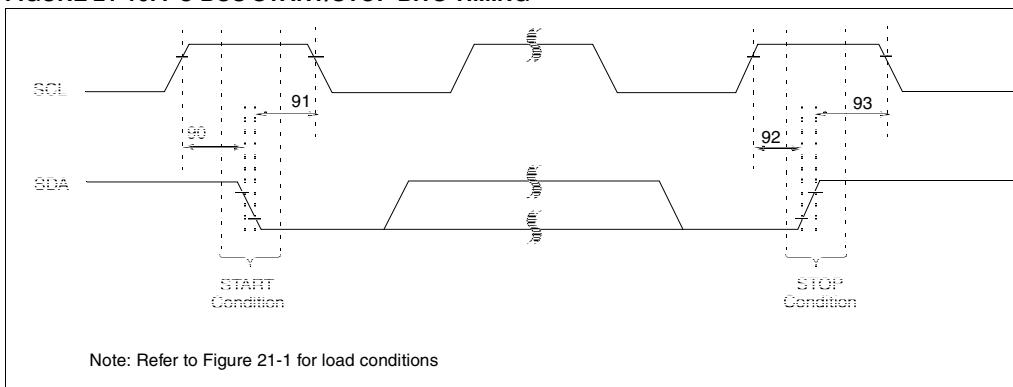
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C6X

Applicable Devices | 61 | 62 | 62A | R62 | 63 | R63 | 64 | 64A | R64 | 65 | 65A | R65 | 66 | 67 |

FIGURE 21-10: I²C BUS START/STOP BITS TIMING



Note: Refer to Figure 21-1 for load conditions

TABLE 21-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90*	TSU:STA	START condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
			400 kHz mode	600	—	—		
91*	THD:STA	START condition Hold time	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
			400 kHz mode	600	—	—		
92*	TSU:STO	STOP condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	STOP condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

PIC16C6X

Applicable Devices | 61 | 62 | 62A | R62 | 63 | R63 | 64 | 64A | R64 | 65 | 65A | R65 | 66 | 67 |

FIGURE 23-12: TYPICAL IDD vs. FREQUENCY (RC MODE @ 22 pF, 25°C)

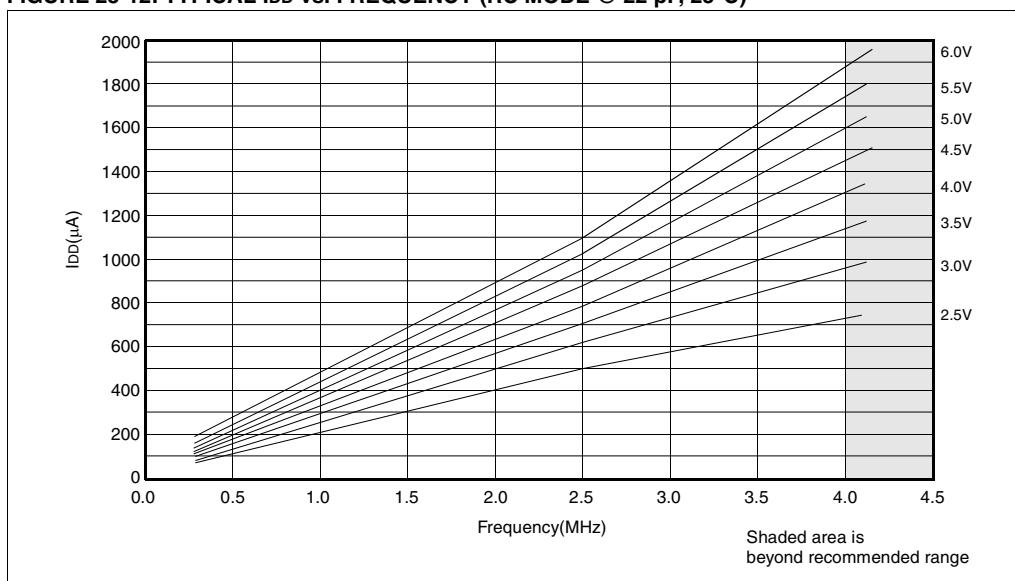
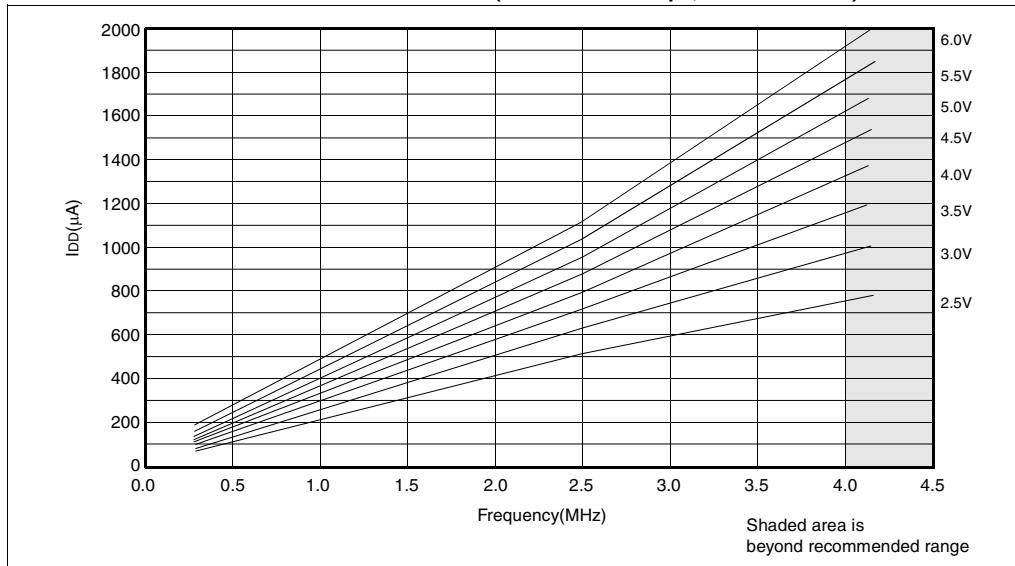


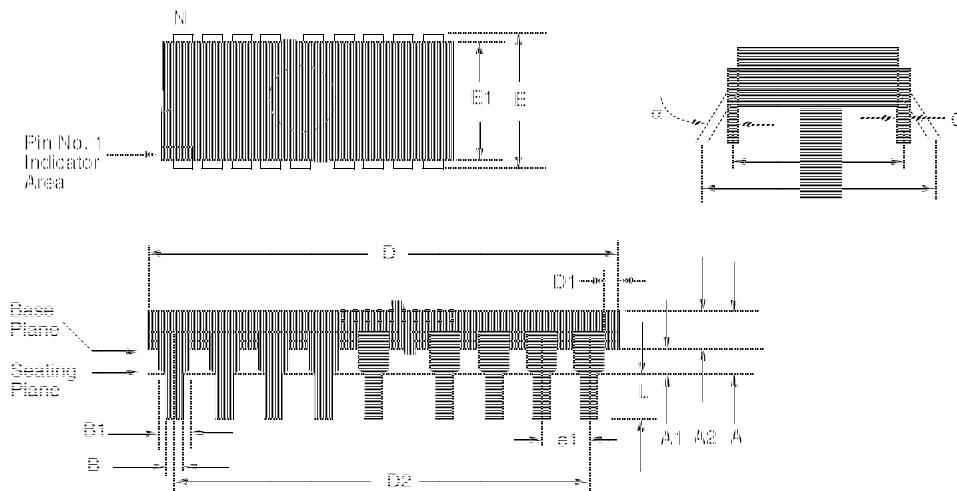
FIGURE 23-13: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 22 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

24.7 28-Lead Ceramic CERDIP Dual In-line with Window (300 mil) (JW)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Package Group: Ceramic CERDIP Dual In-Line (CDP)

Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	3.30	5.84		.130	0.230	
A1	0.38	—		0.015	—	
A2	2.92	4.95		0.115	0.195	
B	0.35	0.58		0.014	0.023	
B1	1.14	1.78	Typical	0.045	0.070	Typical
C	0.20	0.38	Typical	0.008	0.015	Typical
D	34.54	37.72		1.360	1.485	
D2	32.97	33.07	Reference	1.298	1.302	Reference
E	7.62	8.25		0.300	0.325	
E1	6.10	7.87		0.240	0.310	
e	2.54	2.54	Typical	0.100	0.100	Typical
eA	7.62	7.62	Reference	0.300	0.300	Reference
eB	—	11.43		—	0.450	
L	2.92	5.08		0.115	0.200	
N	28	28		28	28	
D1	0.13	—		0.005	—	

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